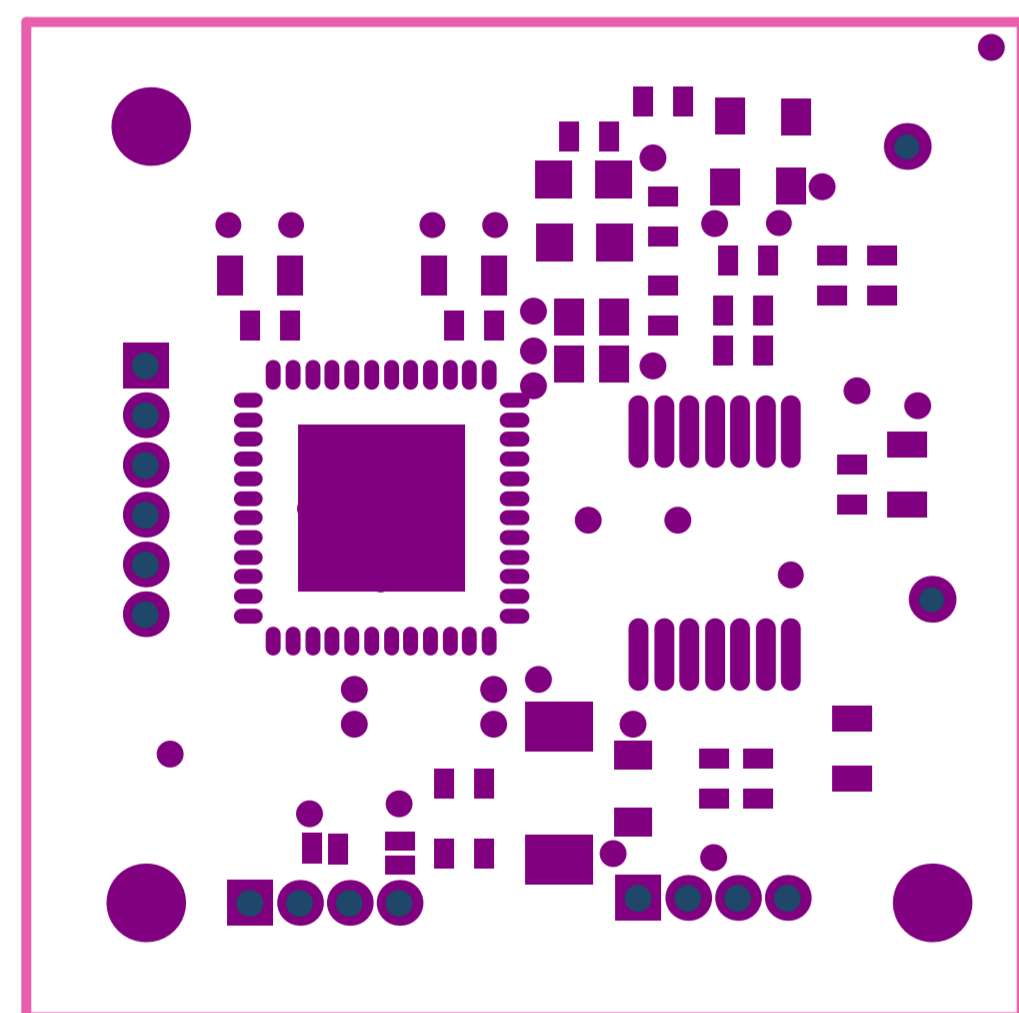
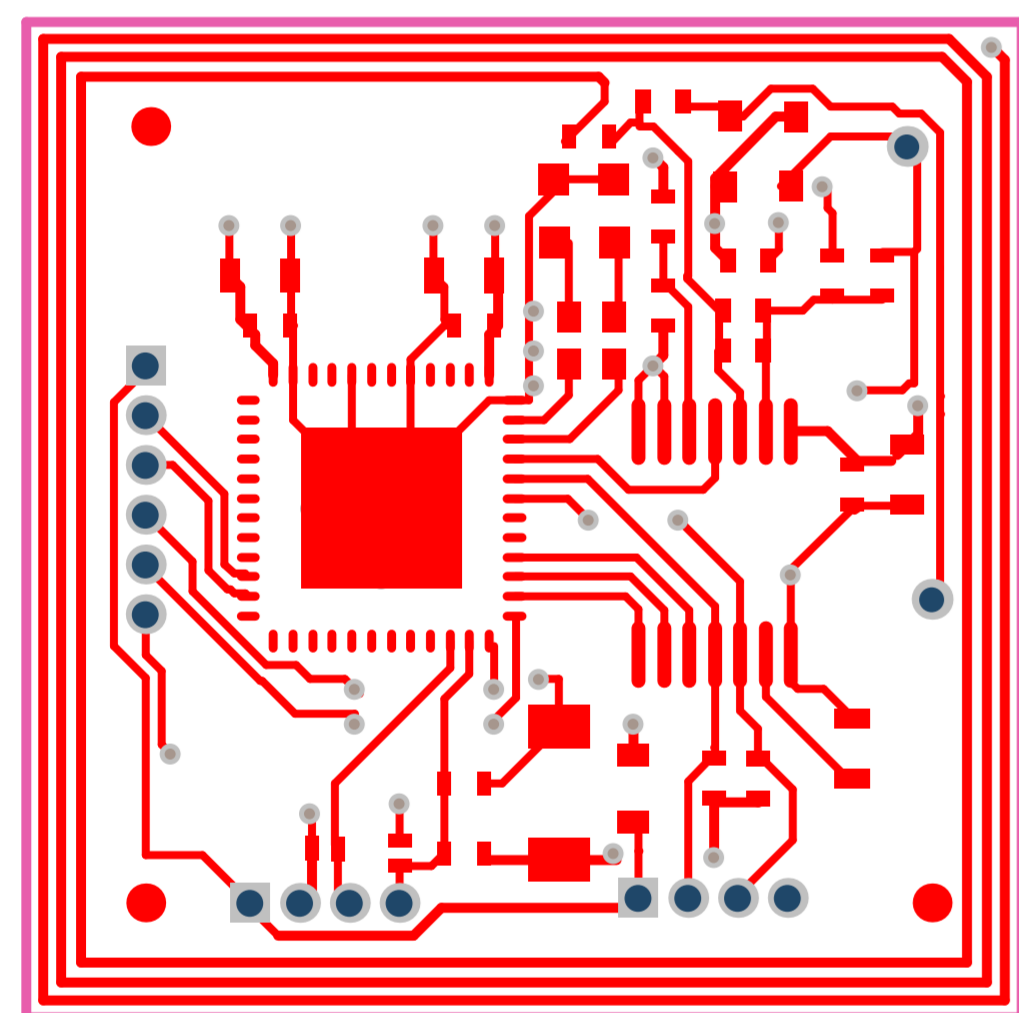


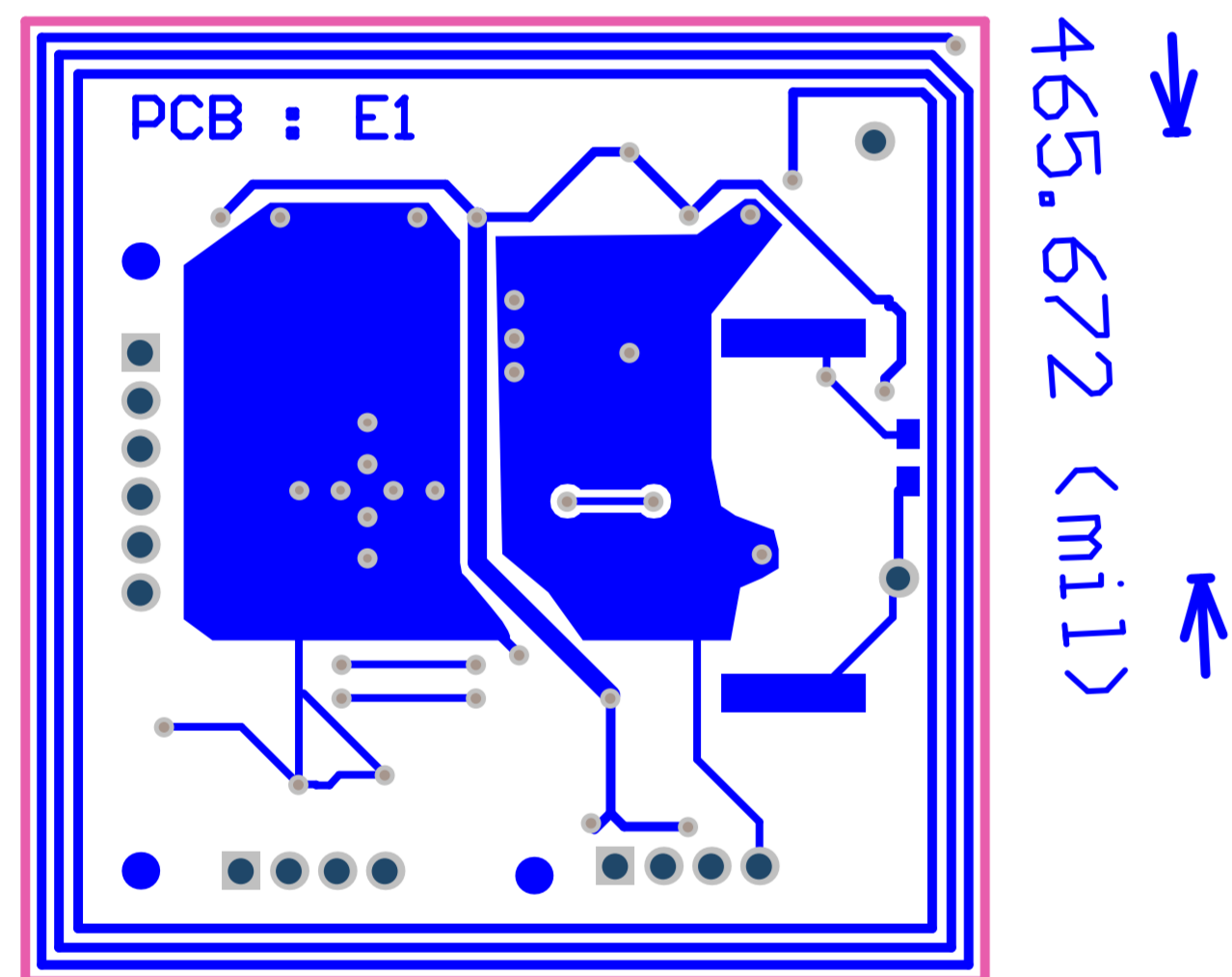
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA00230	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 6/16/2014 3:05:24 PM	TEXAS INSTRUMENTS	



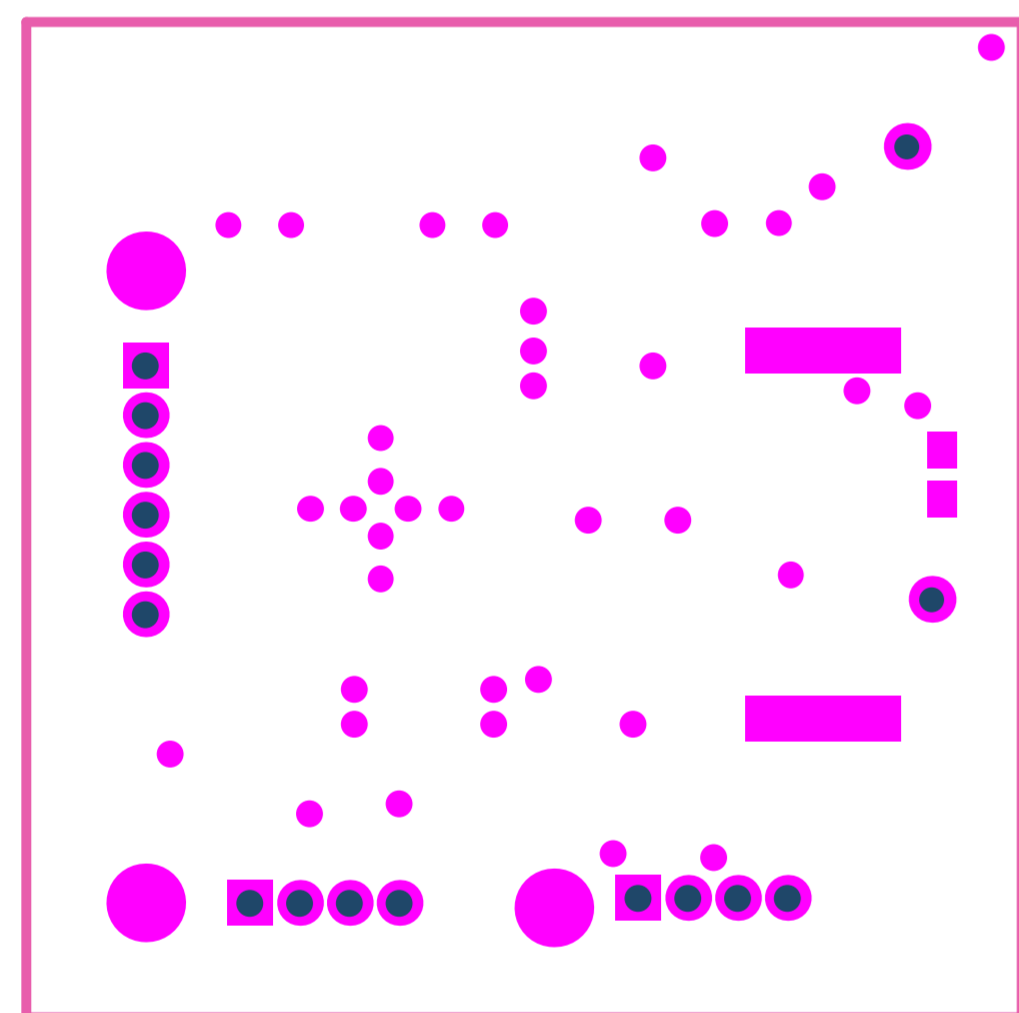
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA00230	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 6/16/2014 3:05:25 PM	TEXAS INSTRUMENTS	



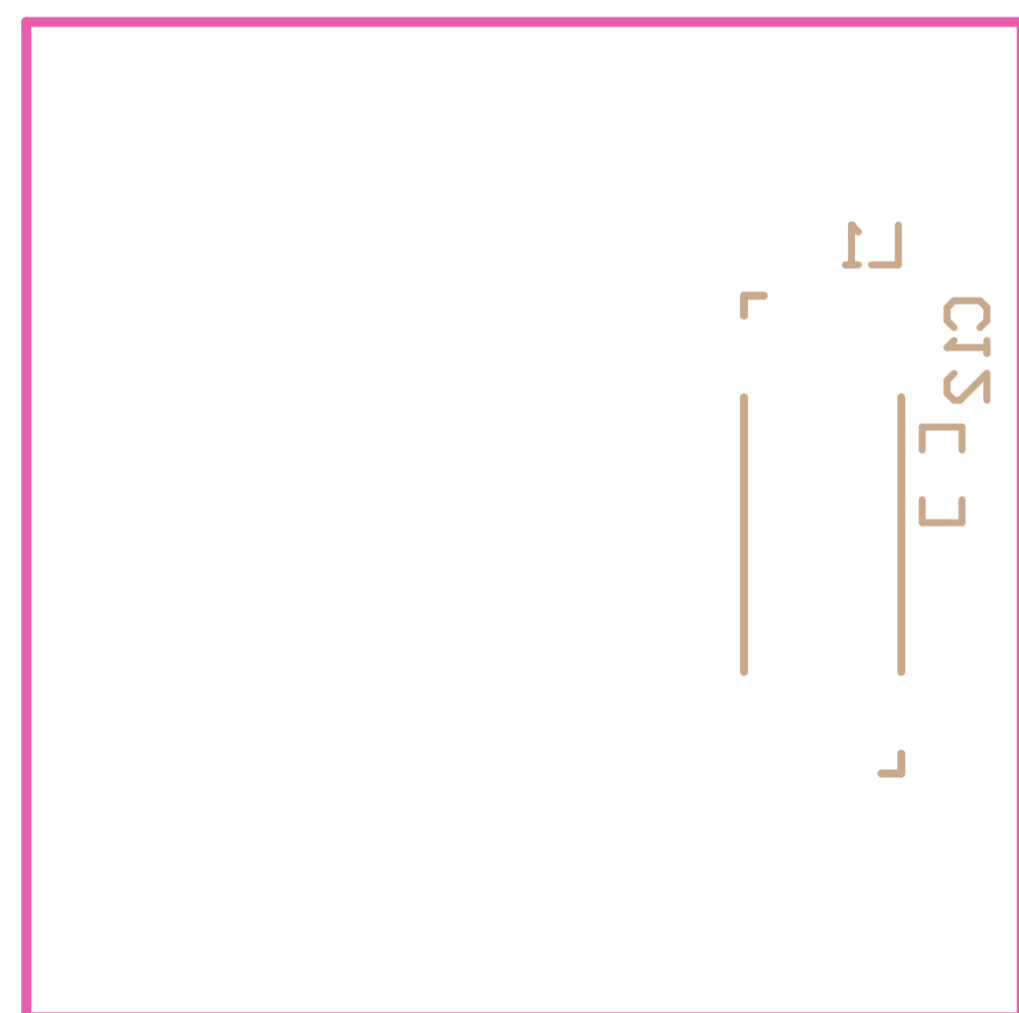
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA00230	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 6/16/2014 3:05:25 PM	TEXAS INSTRUMENTS	



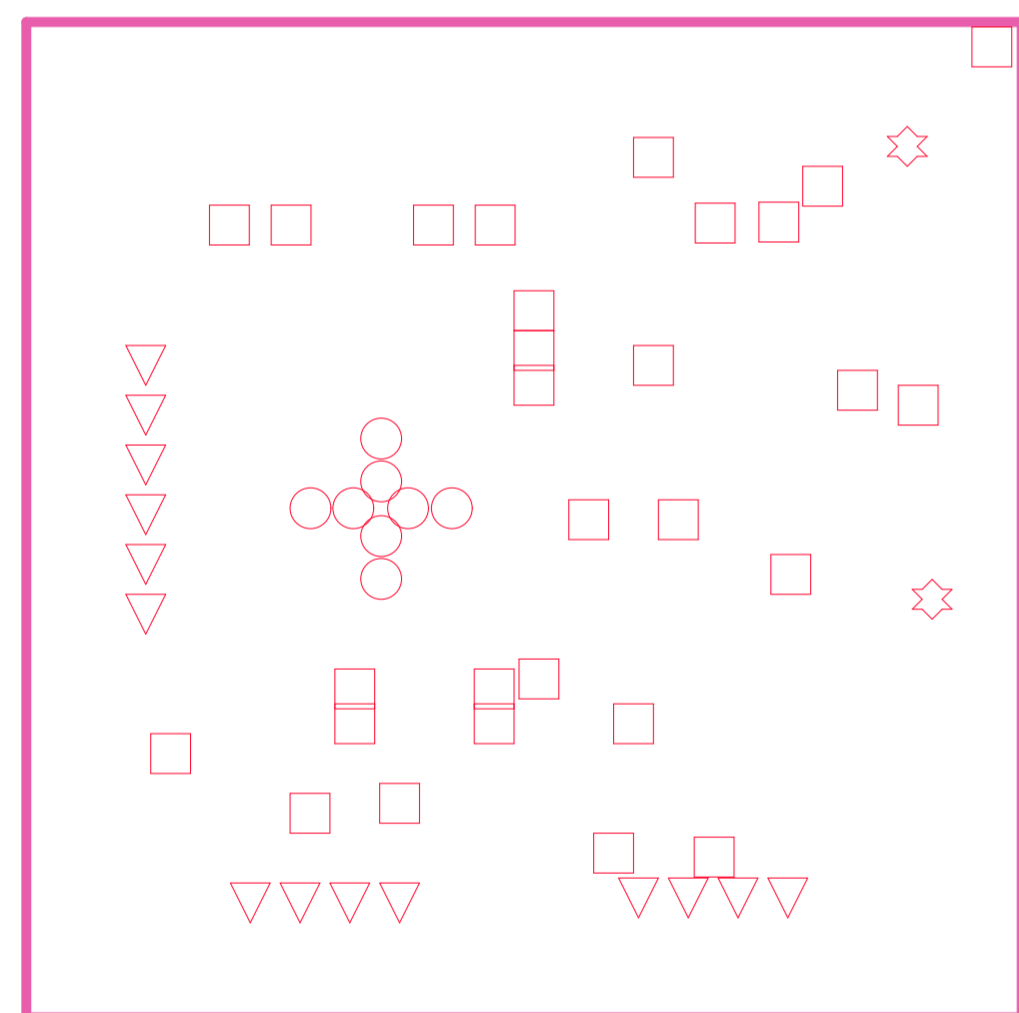
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA00230	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 6/16/2014 3:05:26 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA00230	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 6/16/2014 3:05:26 PM	TEXAS INSTRUMENTS	



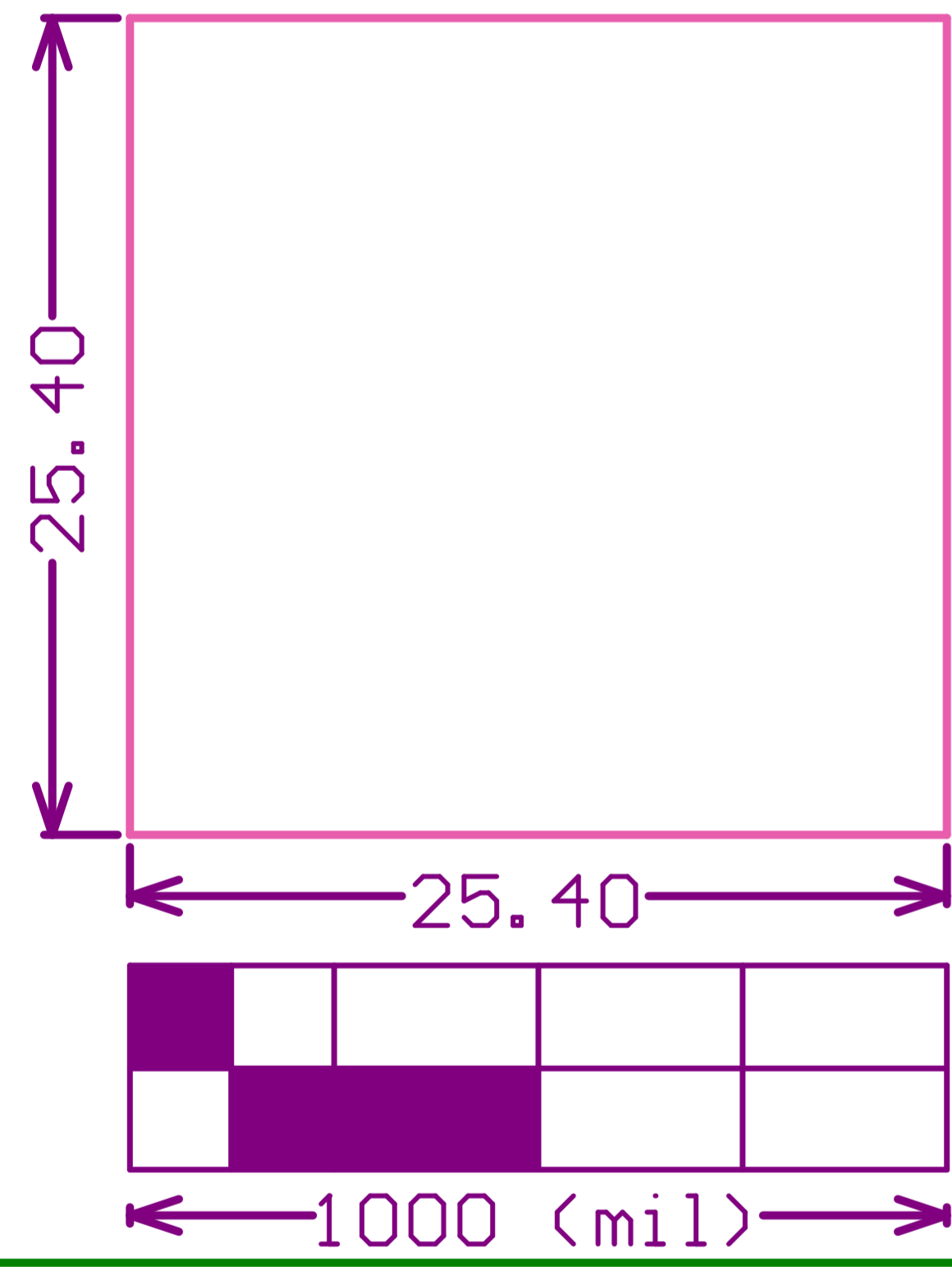
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA00230	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 6/16/2014 3:05:27 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
○	8	7.874mil (0.2mm)	PTH	Round
□	29	10mil (0.254mm)	PTH	Round
☆	2	24mil (0.61mm)	PTH	Round
▽	14	26mil (0.66mm)	PTH	Round
	53 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA00230	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 6/16/2014 3:05:27 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA00230	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 6/16/2014 3:05:27 PM	TEXAS INSTRUMENTS	

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